ENVIRONMENTAL AND PACKAGE TESTING DATA FOR MLP65					
Stress	**Sample Size**	**Device Hr./Cyc**	**Condition**	**Total Fails**	**Fail Percentage**
85/85	165	51,700	85°C, 85%RH	0	0.00
BOND INT	600	450,000	200°C + N2	0	0.00
HAST	1,310	131,000	130°C, 85%RH	0	0.00
Solder Dunk	240	720	260°C, 10 SEC.	0	0.00
Pressure Pot	1,745	167,520	121°, 15 PSIG	0	0.00
Solderability	285	2,280	883 M2003	0	0.00
Temp Cycle	1,790	1,027,500	−65°C−150°C	0	0.00